## Advanced 2-Wire Serial E ${ }^{2}$ PROM with Block Lock ${ }^{\text {TM }}$ Protection

## FEATURES

## -2.7V to 5.5V Power Supply

-Low Power CMOS
-Active Read Current Less Than 1mA
-Active Write Current Less Than 3mA
—Standby Current Less Than $1 \propto A$
-Internally Organized 8192 x 8
-New Programmable Block Lock Protection
—Software Write Protection
—Programmable hardware Write Protect
-Block Lock ( $0,1 / 4,1 / 2$, or all of the E ${ }^{2}$ PROM array)
-2 Wire Serial Interface

- Bidirectional Data Transfer Protocol
- 32 Byte Page Write Mode
-Minimizes Total Write Time Per Byte
- Self Timed Write Cycle
-Typical Write Cycle Time of 5ms
-High Reliability
—Endurance: 100,000 Cycles
—Data Retention: 100 Years
-Available Packages
—8-Lead PDIP
-8-Lead SOIC (JEDEC)
-14-Lead SOIC (JEDEC)
-20-Lead TSSOP


## DESCRIPTION

The X24645 is a CMOS 65,536 -bit serial $E^{2}$ PROM, internally organized $8192 \times 8$. The X24645 features a serial interface and software protocol allowing operation on a simple two wire bus.
Two device select inputs $\left(\mathrm{S}_{1}, \overline{\mathrm{~S}}_{2}\right)$ allow up to four devices to share a common two wire bus.

A Write Protect Register at the highest address location, 1FFFh, provides three new write protection features: Software Write Protect, Block Write Protect, and Hardware Write Protect. The Software Write Protect feature prevents any nonvolatile writes to the X24645 until the WEL bit in the write protect register is set. The Block Write Protection feature allows the user to individually write protect four blocks of the array by programming two bits in the write protect register. The Programmable Hardware Write Protect feature allows the user to install the X24645 with WP tied to $\mathrm{V}_{\mathrm{cc}}$, program the entire memory array in place, and then enable the hardware write protection by programming a WPEN bit in the write protect register. After this, selected blocks of the array, including the write protect register itself, are permanently write protected, as long as WP remains HIGH.

## FUNCTIONAL DIAGRAM



## X24645

ICmic $E^{2}$ PROMs are designed and tested for applications requiring extended endurance. Inherent data retention is greater than 100 years.

## PIN DESCRIPTIONS Serial Clock (SCL)

The SCL input is used to clock all data into and out of the device.

## Serial Data (SDA)

SDA is a bidirectional pin used to transfer data into and out of the device. It is an open drain output and may be wire-ORed with any number of open drain or open collector outputs.

An open drain output requires the use of a pull-up resistor. For selecting typical values, refer to the Pullup resistor selection graph at the end of this data sheet.

## Device Select ( $\mathbf{S}_{1}, \bar{S}_{2}$ )

The device select inputs ( $\mathrm{S}_{1}, \mathrm{~S}_{2}$ ) are used to set the first and second bits of the 8 -bit slave address. This allows up to four X24645 devices to share a common bus. These inputs can be static or actively driven. If
used statically they must be tied to $\mathrm{V}_{\mathrm{SS}}$ or $\mathrm{V}_{\mathrm{CC}}$ as appropriate. If actively driven, they must be driven with CMOS levels (driven to $\mathrm{V}_{\mathrm{Cc}}$ or $\mathrm{V}_{\mathrm{SS}}$ ).

## Write Protect (WP)

The write protect input controls the hardware write protect feature. When held LOW, hardware write protection is disabled and the X24645 can be written normally. When this input is held HIGH, and the WPEN bit in the write protect register is set HIGH, write protection is enabled, and nonvolatile writes are disabled to the selected blocks as well as the write protect register itself.

## PIN NAMES

| Symbol | Description |
| :--- | :--- |
| $\mathrm{S}_{1}, \overline{\mathrm{~S}}_{2}$ | Device Select Inputs |
| SDA | Serial Data |
| SCL | Serial Clock |
| WP | Write Protect |
| $\mathrm{V}_{S S}$ | Ground |
| $\mathrm{V}_{\mathrm{CC}}$ | Supply Voltage |
| NC | No Connect |

PIN CONFIGURATIONS


## DEVICE OPERATION

The X24645 supports a bidirectional bus oriented protocol. The protocol defines any device that sends data onto the bus as a transmitter, and the receiving device as the receiver. The device controlling the transfer is a master and the device being controlled is the slave. The master will always initiate data transfers, and provide the clock for both transmit and receive operations. Therefore, the X24645 will be considered a slave in all applications.

## Clock and Data Conventions

Data states on the SDA line can change only during SCL LOW. SDA state changes during SCL HIGH are
reserved for indicating start and stop conditions. Refer to Figures 1 and 2.

## Start Condition

All command are preceded by the start condition, which is a HIGH to LOW transition of SDA when SCL is
HIGH. The X24645 continuously monitors the SDA and SCL lines for the start condition and will not respond to any command until this condition has been met.

Figure 1. Data Validity


Notes: (5) Typical values are for $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ and nominal supply voltage ( 5 V )
(6) twr is the minimum cycle time from the system perspective when polling techniques are not used. It is the maximum time the device requires to perform the internal write operation.

Figure 2. Definition of Start and Stop


## X24645

## Stop Condition

All communications must be terminated by a stop condition, which is a LOW to HIGH transition of SDA when SCL is HIGH. The stop condition is also used to place the device into the standby power mode after a read sequence. A stop condition can only be issued after the transmitting device has released the bus.

## Acknowledge

Acknowledge is a software convention used to indicate successful data transfer. The transmitting device, either master or slave, will release the bus after transmitting eight bits. During the ninth clock cycle the receiver will pull the SDA line LOW to acknowledge that it received the eight bits of data. Refer to Figure 3.

The X24645 will respond with an acknowledge after recognition of a start condition and its slave address. If both the device and a write operation have been selected, the X24645 will respond with an acknowledge after the receipt of each subsequent 8-bit word.

In the read mode the X24645 will transmit eight bits of data release the SDA line and monitor the line for an acknowledge. If an acknowledge is detected and no stop condition is generated by the master, the X24645 will continue to transmit data. If an acknowledge is not detected, the X24645 will terminate further data transmissions. The master must then issue a stop condition to return the X24645 to the standby power mode and place the device into a known state.

Figure 3. Acknowledge Response From Receiver


## DEVICE ADDRESSING

Following a start condition the master must output the address of the slave it is accessing (see Figure 4). The next two bits are the device select bits. A system could have up to four X24645's on the bus. The four addresses are defined by the state of the $S_{1}$ and $S_{2}$ inputs. $\mathrm{S}_{2}$ of the slave address must be the inverse of the $\mathrm{S}_{2}$ input pin.

Figure 4. Slave Address


The next five bits of the slave address are an extension of the array's address and are concatenated with
the eight bits of address in the byte address field, providing direct access to the whole $8192 \times 8$ array.

The last bit of the slave address defines the operation to be performed. When set HIGH a read operation is selected, when set LOW, a write operation is selected.

Following the start condition, the X24645 monitors the SDA bus comparing the slave address being transmitted with its slave address device type identifier. Upon a correct compare the X24645 outputs an acknowledge on
the SDA line. Depending on the state of the $R \bar{W}$ bit, the X24645 will execute a read or write operation.

## WRITE OPERATIONS Byte Write

For a write operation, the X24645 requires a second address field. This address field is the byte address, comprised of eight bits, providing access to any one of 8192 words in the array. Upon receipt of the byte address, the X24645 responds with an acknowledge and awaits the next eight bits of data, again responding with an acknowledge The master then terminates the transfer by generating a stop condition, at which time the X24645 begins the internal write cycle to the nonvolatile memory. While the internal write cycle is in progress the X24645 inputs are disabled, and the device will not respond to any requests from the master. Refer to Figure 5 for the address, acknowledge and data transfer sequence.

Figure 5. Byte Write


## X24645

## Page Write

The X24645 is capable of a 32-byte page write operation. It is initiated in the same manner as the byte write operation, but instead of terminating the write cycle after the first data word is transferred, the master can transmit up to thirty-one more bytes. After the receipt of each byte, the X24645 will respond with an acknowledge.

## After the receipt of each byte, the five low order address bits are internally incremented by one. The high

order eight bits of the address remain constant. If the master should transmit more than 32 bytes prior to generating the stop condition, the address counter will "roll over" and the previously written data will be overwritten As with the byte write operation, all inputs are disabled until completion of the internal write cycle. Refer to Figure 6 for the address, acknowledge, and data transfer sequence

## Acknowledge Polling

The Max Write Cycle Time can be significantly reduced using Acknowledge Polling. To initiate Acknowledge
Polling, the master issues a start condition followed by the Slave Address Byte for a write or read operation. If
the device is still busy with the high voltage cycle, then no ACK will be returned. If the device has completed
the write operation, an ACK will be returned and the host can then proceed with the read or write operation.
Refer to Flow 1.

Flow 1. ACK Polling Sequence


Figure 6. Page Write


## READ OPERATIONS

Read operations are initiated in the same manner as write operations with the exception that the R/W bit of
the slave address is set HIGH. There are three basic read operations: current address read, random read and sequential read.

It should be noted that the ninth clock cycle of the read operation is not a "don't care." To terminate a read operation, the master must either issue a stop condition during the ninth cycle or hold SDA HIGH during the ninth clock cycle and then issue a stop condition.

## Current Address Read

Internally the X24645 contains an address counter that maintains the address of the last byte read, incremented by one or the exact address of the last byte written. Therefore, if the last access read was to address n , the next read operation would access data from address $n+1$. Upon receipt of the slave address with the $R / \bar{W}$ set HIGH, the X24645 issues an acknowledge
and transmits the byte. The read operation is terminated by the master; by not responding with an acknowledge and by issuing a stop condition. Refer to Figure 7 for the sequence of address, acknowledge and data transfer.

## Random Read

Random read operations allow the master to access any memory location in a random manner. Prior to issuing
the slave address with the $\mathrm{R} / \overline{\mathrm{W}}$ bit set HIGH , the master must first perform a "dummy" write operation.
The master issues the start condition, and the slave address with the R/W bit set LOW, followed by the byte address it is to read. After the word address acknowledge, the master immediately reissues the start condition
and the slave address with the $\mathrm{R} / \overline{\mathrm{W}}$ bit set HIGH. This will be followed by an acknowledge from the X24645 and then by the data byte. The read operation is terminated by the master; by not responding with an acknowledge and by issuing a stop condition. Refer to Figure 8 for the address, acknowledge and data transfer sequence.

Figure 7. Current Address Read


Figure 8. Random Read


## X24645

## Sequential Read

Sequential reads can be initiated as either a current address read or random access read. The first byte is transmitted as with the other modes, however, the master now responds with an acknowledge, indicating it requires additional data. The X24645 continues to output data for each acknowledge received. The read operation is terminated by the master; by not responding with an acknowledge and then issuing a stop condition.

The data output is sequential, with the data from address n followed by the data from $\mathrm{n}+1$. The address counter for read operations increments all address bits, allowing the entire memory contents to be serially read during one operation. At the end of the address space (address 8191), the counter "rolls over" to 0 and the X24645 continues to output data for each acknowledge received. Refer to Figure 9 for the address, acknowledge and data transfer sequence.

Figure 9. Sequential Read


Figure 10. Typical System Configuration


## WRITE PROTECT REGISTER

The Write Protect Register (WPR) is located at the highest address, 1FFFh.

Figure 11. Write Protect Register
WPR (ADDR = 1FFFh)

| $\mathbf{7}$ | $\mathbf{6}$ | $\mathbf{5}$ | $\mathbf{4}$ | $\mathbf{3}$ | $\mathbf{2}$ | $\mathbf{1}$ | $\mathbf{0}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $W P E N$ | 0 | 0 | BP 1 | BP 0 | RWEL | WEL | 0 |

2783 ILL F15.1
WPR. 1 = WEL
-- "Write Enable" Latch (Volatile)
$0=$ Write enable latch reset, writes disabled $1=$ Write enable latch set, writes enabled

If WEL = " 0 "then "no ACK" after first byte of input data.
WPR. 2 = RWEL
-- "Register Write Enable" Latch (Volatile)
$0=$ Register write enable latch reset, writes disabled
1 = Register write enable latch set, writes enabled
WPR.3, WPR. 4 = BPO, BP1
-- Block Protect Bits (Nonvolatile)
(See Block Protect section for definition)
WPR. 7 = WPEN

- Write Protect Enable Bit (Nonvolatile)
(See Hardware Write Protect section for definition)


## Writing to the Write Protect Register

The Write Protect Register is written by performing a random write of one byte directly to address, 1FFFh. If a page write is performed starting with any address other than 1FFF, the byte in the array at address
1FFFh will be written instead of the Write Protect Register (assuming writes are not disabled by the block protect register).

The state of the Write Protect Register can be read by performing a random read at address 1FFFh at any time. If a sequential read starting at any other address than 1FFFh is performed, the contents of the byte in
the array at 1FFFh is read out instead of the Write Protect Register.

WEL and RWEL are volatile latches that power-up in the LOW (disabled) state. A write to any address other than 1FFFh, where the Write Protect Register is located, will be ignored (no ack) until the WEL bit is set HIGH. The WEL bit is set by writing 0000001x to address 1FFFh. Once set, WEL remains HIGH until either reset (by writing 00000000 to 1 FFFh) or until the part powers-up again. The RWEL bit controls writes to the block protect bits. RWEL is set by first setting WEL to " 1 " and then writing $0000011 x$ to address 1FFFh. RWEL must be set in order to change the block protect bits, BPO and BP1, or the WPEN bit. RWEL is reset when the block protect or WPEN bits are changed, or when the part powers-up again.

## Programming the BP or WPEN Bits

A three step sequence is required to change the nonvolatile Block Protect or Write Protect Enable:

1) Set WEL $=1$ (write 00000010 to address 1 FFFh, volatile write cycle)
(Start)
2) Set RWEL = 1 (write 00000110 to address 1FFFh, volatile write cycle)
(Start)
3) Set BP1, BP0, and/or WPEN bits (Write w00yz010 to address 1FFFh)
$\mathrm{w}=\mathrm{WPEN}, \mathrm{y}=\mathrm{BP} 1, \mathrm{Z}=\mathrm{BP} 0$,
(Stop)
Step 3 is a nonvolatile write cycle, requiring 10 ms to complete. RWEL is reset to "0"
by this write cycle, requiring another write cycle to set RWEL again before the block protect bits can be changed. RWEL must be
" 0 in step 3 ; if w00yz110 is written to address 1FFFh, RWEL is set but WPEN, BP1 and BPO are not changed (the device remains at step 2).

## Block Protect Bits

The Block Protect Bits BP0 and BP1 determine which blocks of the memory are write-protected:

## Table 1. Block Protect Bits

| BP1 | BP0 | Protected <br> Addresses |  |
| :---: | :---: | :--- | :--- |
| 0 | 0 | None |  |
| 0 | 1 | 1800h-1FFFh | Upper 1/4 |
| 1 | 0 | $1000 \mathrm{~h}-1$ FFFh | Upper 1/2 |
| 1 | 1 | 0000h-1FFFh | Full Array (WPR <br> not included) |

2783 FRM T02

## Programmable Hardware Write Protect

The Write Protect (WP) pin and the Write Protect Enable (WPEN) bit in the Write Protect Register control the programmable hardware write protect feature. Hardware write protection is enabled when the WP pin is HIGH and the WPEN bit is " 1 ", and disabled when either the WP pin is LOW or the WPEN bit is " 0 ".
When the chip is hardware write-protected, nonvolatile writes are disabled to the Write Protect Register,
including the BP bits and the WPEN bit itself, as well as to block-protected sections in the memory array.
Only the sections of the memory array that are not block-protected can be written. Note that since the WPEN bit is write-protected, it cannot be changed back to a LOW state, and write protection is disabled
as long as the the WP pin is held HIGH. Table 2 defines the write protection status for each state of WPEN and WP.

Table 2. Write Protect Status Table

| WP | WPEN | Memory Array <br> (Not Block <br> Protected) | Memory Array <br> (Block Protected) | BP Bits | WPEN Bit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| L | X | Writable | Protected | Writable | Writable |
| X | 0 | Writable | Protected | Writable | Writable |
| H | 1 | Writable | Protected | Protected | Protected |

## ABSOLUTE MAXIMUM RATINGS*

Temperature under Bias
X24645...................................... $65^{\circ} \mathrm{C}$ to $+135^{\circ} \mathrm{C}$
Storage Temperature........................ $-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$
Voltage on any Pin with
Respect to $V_{S S}$ -1 V to +7 V
D.C. Output Current 5 mA
Lead Temperature (Soldering 10 seconds)
$300^{\circ} \mathrm{C}$

## RECOMMENDED OPERATING CONDITIONS

| Temperature | Min. | Max. |
| :---: | :---: | :---: |
| Commercial | $0^{\circ} \mathrm{C}$ | $+70^{\circ} \mathrm{C}$ |
| Industrial | $-40^{\circ} \mathrm{C}$ | $+85^{\circ} \mathrm{C}$ |
| Military | $-55^{\circ} \mathrm{C}$ | $+125^{\circ} \mathrm{C}$ |

## *COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and the functional operation
of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

| Supply Voltage | Limits |
| :---: | :---: |
| X24645 | 4.5 V to 5.5 V |
| $\mathrm{X} 24645-2.7$ | 2.7 V to 5.5 V |

2783 FRM T05

## D.C. OPERATING CHARACTERISTICS

| Symbol | Parameter | Limits |  | Units | Test Conditions |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min. | Max. |  |  |
| $\mathrm{I}_{\mathrm{CC} 1}$ | $\mathrm{V}_{\text {CC }}$ Supply Current (Read) |  | 1 | mA | $\mathrm{SCL}=\mathrm{V}_{\mathrm{CC}} \mathrm{X} 0.1 / \mathrm{V}_{\mathrm{CC}} \times 0.9$ Levels @ 100 KHz, SDA $=$ Open, All Other Inputs $=\mathrm{V}_{S S}$ or $\mathrm{V}_{\mathrm{CC}}-0.3 \mathrm{~V}$ |
| $\mathrm{I}_{\text {CC2 }}$ | $V_{\text {CC }}$ Supply Current (Write) |  | 3 | mA |  |
| $\mathrm{I}_{\text {SB1 }}{ }^{(1)}$ | $\mathrm{V}_{\text {CC }}$ Standby Current |  | 50 | $\propto \mathrm{A}$ | $\begin{aligned} & \mathrm{SCL}=\mathrm{SDA}=\mathrm{V}_{\mathrm{CC}}, \text { All Other } \\ & \text { Inputs }=\mathrm{V}_{\mathrm{SS}} \text { or } \mathrm{V}_{\mathrm{CC}}-0.3 \mathrm{~V}, \\ & \mathrm{~V}_{\mathrm{CC}}=5 \mathrm{~V} \pm 10 \% \end{aligned}$ |
| $\mathrm{I}_{\mathrm{SB} 2}{ }^{(1)}$ | $\mathrm{V}_{\text {CC }}$ Standby Current |  | 1 | $\propto \mathrm{A}$ | $\begin{aligned} & \mathrm{SCL}=\mathrm{SDA}=\mathrm{V}_{\mathrm{CC}}, \text { All Other } \\ & \text { Inputs }=\mathrm{V}_{\mathrm{SS}} \text { or } \mathrm{V}_{\mathrm{CC}}-0.3 \mathrm{~V}, \\ & \mathrm{~V}_{\mathrm{CC}}=2.7 \mathrm{~V} \end{aligned}$ |
| ILI | Input Leakage Current |  | 10 | $\propto \mathrm{A}$ | $\mathrm{V}_{\text {IN }}=\mathrm{V}_{\text {SS }}$ to $\mathrm{V}_{\mathrm{CC}}$ |
| lo | Output Leakage Current |  | 10 | $\propto \mathrm{A}$ | $\mathrm{V}_{\text {OUT }}=\mathrm{V}_{\text {SS }}$ to $\mathrm{V}_{\text {CC }}$ |
| $\mathrm{V}_{\mathrm{IL}}{ }^{(2)}$ | Input LOW Voltage | -1 | $\mathrm{V}_{\mathrm{CC}} \times 0.3$ | V |  |
| $\mathrm{V}_{1 \mathrm{H}^{(2)}}$ | Input HIGH Voltage | $\mathrm{V}_{\mathrm{CC}} \times 0.7$ | $\mathrm{V}_{\mathrm{CC}}+0.5$ | V |  |
| $\mathrm{V}_{\mathrm{OL}}$ | Output LOW Voltage |  | 0.4 | V | $\mathrm{l}_{\mathrm{OL}}=3 \mathrm{~mA}, \mathrm{~V}_{\mathrm{CC}}=4.5 \mathrm{~V}$ |

2783 FRM T06.2
CAPACITANCE $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}, \mathrm{f}=1 \mathrm{MHz}, \mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}$

| Symbol | Parameter | Max. | Units | Test Conditions |
| :---: | :--- | :---: | :---: | :---: |
| $\mathrm{C}_{\mathrm{I} / \mathrm{O}}{ }^{(3)}$ | Input/Output Capacitance $(\mathrm{SDA})$ | 8 | pF | $\mathrm{V}_{\mathrm{I} / \mathrm{O}}=0 \mathrm{~V}$ |
| $\mathrm{C}_{\mathbb{I N}}{ }^{(3)}$ | Input Capacitance $\left(\mathrm{S}_{1}, \overline{\mathrm{~S}}_{2}, \mathrm{SCL}\right)$ | 6 | pF | $\mathrm{V}_{\mathbb{I N}}=0 \mathrm{~V}$ |

2783 FRM T07. 1
Notes: (1)Must perform a stop command prior to measurement.
(2) $\mathrm{V}_{\mathrm{IL}} \mathrm{min}$. and $\mathrm{V}_{\mathrm{IH}}$ max. are for reference only and are not $100 \%$ tested. (3)This parameter is periodically sampled and not $100 \%$ tested.
A.C. CONDITIONS OF TEST

| Input Pulse Levels | $\mathrm{V}_{\mathrm{CC}} \times 0.1$ to $\mathrm{V}_{\mathrm{CC}} \times 0.9$ |
| :--- | :---: |
| Input Rise and <br> Fall Times | 10 ns |
| Input and Output <br> Timing Levels | $\mathrm{V}_{\mathrm{CC}} \times 0.5$ |

2783 FRM T08

EQUIVALENT A.C. LOAD CIRCUIT

A.C. OPERATING CHARACTERISTICS (Over the recommended operating conditions, unless otherwise specified.) Read \& Write Cycle Limits

| Symbol | Parameter | Min. | Max. | Units |
| :---: | :---: | :---: | :---: | :---: |
| $\mathrm{f}_{\text {SCL }}$ | SCL Clock Frequency | 0 | 100 | KHz |
| $\mathrm{T}_{1}$ | Noise Suppression Time Constant at SCL, SDA Inputs |  | 100 | ns |
| $\mathrm{t}_{\mathrm{AA}}$ | SCL LOW to SDA Data Out Valid | 0.3 | 3.5 | $\propto$ S |
| $\mathrm{t}_{\text {BUF }}$ | Time the Bus Must Be Free Before a New Transmission Can Start | 4.7 |  | $\propto$ S |
| $\mathrm{t}_{\text {HD: }}$ STA | Start Condition Hold Time | 4 |  | $\propto$ s |
| tLow | Clock LOW Period | 4.7 |  | $\propto$ S |
| $\mathrm{t}_{\text {HIGH }}$ | Clock HIGH Period | 4 |  | $\propto$ |
| tsu:STA | Start Condition Setup Time (for a Repeated Start Condition) | 4.7 |  | $\propto$ S |
| $\mathrm{t}_{\text {HD: }}$ DAT | Data In Hold Time | 0 |  | $\propto$ S |
| $\mathrm{t}_{\text {SU: }}$ DAT | Data In Setup Time | 250 |  | ns |
| $t_{R}$ | SDA and SCL Rise Time |  | 1 | $\propto$ S |
| $\mathrm{t}_{\mathrm{F}}$ | SDA and SCL Fall Time |  | 300 | ns |
| $\mathrm{t}_{\text {Su:STO }}$ | Stop Condition Setup Time | 4.7 |  | $\propto$ S |
| $t_{\text {DH }}$ | Data Out Hold Time | 300 |  | ns |

2783 FRM T09.2
POWER-UP TIMING ${ }^{(4)}$

| Symbol | Parameter | Max. | Units |
| :---: | :---: | :---: | :---: |
| tPUR | Power-up to Read Operation | 1 | ms |
| tPuw | Power-up to Write Operation | 5 | ms |

[^0]
## Bus Timing



## Write Cycle Limits

| Symbol | Parameter | Min. | Typ. $^{(5)}$ | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{T}_{\mathrm{WR}}{ }^{(6)}$ | Write Cycle Time |  | 5 | 10 | ms |

The write cycle time is the time from a valid stop condition of a write sequence to the end of the internal erase/program cycle. During the write cycle, the

X24645 bus interface circuits are disabled, SDA is allowed to remain HIGH, and the device does not respond to its slave address.

## Bus Timing

SDA

Notes: (5)Typical values are for $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ and nominal supply voltage (5V).
(6)twr is the minimum cycle time to be allowed from the system perspective unless polling techniques are used. It is the maximum time the device requires to automatically complete the internal write operation.

Guidelines for Calculating Typical Values of Bus Pull-Up Resistors


SYMBOL TABLE
$\left.\begin{array}{|cll|}\hline \text { WAVEFORM } & \text { INPUTS } & \text { OUTPUTS } \\ & \begin{array}{l}\text { Must be } \\ \text { steady }\end{array} & \begin{array}{l}\text { Will be } \\ \text { steady }\end{array} \\ & \begin{array}{l}\text { May change } \\ \text { from LOW } \\ \text { to HIGH } \\ \text { May change } \\ \text { from HIGH } \\ \text { to LOW }\end{array} & \begin{array}{l}\text { Will change } \\ \text { from LOW } \\ \text { to HIGH }\end{array} \\ \begin{array}{l}\text { Will change } \\ \text { from HIGH } \\ \text { to LOW }\end{array} \\ \text { Don't Care: } \\ \text { Changes } \\ \text { Allowed } \\ \text { N/A }\end{array} \quad \begin{array}{l}\text { Changing: } \\ \text { State Not } \\ \text { Known }\end{array}\right\}$

## PACKAGING INFORMATION

## 8-LEAD PLASTIC DUAL IN-LINE PACKAGE TYPE P



NOTE:

1. ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS) 2. PACKAGE DIMENSIONS EXCLUDE MOLDING FLASH

## PACKAGING INFORMATION

## 8-LEAD PLASTIC SMALL OUTLINE GULL WING PACKAGE TYPE S



NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

## PACKAGING INFORMATION

## 14-LEAD PLASTIC SMALL OUTLINE GULL WING PACKAGE TYPE S



NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

## PACKAGING INFORMATION

## 20-LEAD PLASTIC, TSSOP PACKAGE TYPE V



NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

## ORDERING INFORMATION



## Part Mark Convention

\begin{tabular}{|c|c|c|}
\hline X24645 \& XG

X \& $$
\begin{aligned}
& \mathrm{P}=8 \text {-Lead Plastic DIP } \\
& \mathrm{S}=14 \text {-Lead SOIC } \\
& \text { Blank }=8 \text {-Lead SOIC (JEDEC) } \\
& V=20-\text { Lead TSSOP } \\
& \mathrm{G}=\text { RoHS compliant lead free }
\end{aligned}
$$ <br>

\hline \& \& $$
\begin{aligned}
& \text { Blank }=4.5 \mathrm{~V} \text { to } 5.5 \mathrm{~V}, 0^{\circ} \mathrm{C} \text { to }+70^{\circ} \mathrm{C} \\
& \mathrm{I}=4.5 \mathrm{~V} \text { to } 5.5 \mathrm{~V},-40^{\circ} \mathrm{C} \text { to }+85^{\circ} \mathrm{C}
\end{aligned}
$$ <br>

\hline \& \& $$
\begin{aligned}
& \mathrm{F}=2.7 \mathrm{~V} \text { to } 5.5 \mathrm{~V}, 0^{\circ} \mathrm{C} \text { to }+70^{\circ} \mathrm{C} \\
& \mathrm{G}=2.7 \mathrm{~V} \text { to } 5.5 \mathrm{~V},-40^{\circ} \mathrm{C} \text { to }+85^{\circ} \mathrm{C}
\end{aligned}
$$ <br>

\hline
\end{tabular}

## LIMITED WARRANTY

Devices sold by Xicor, Inc. are covered by the warranty and patent indemnification provisions appearing in its Terms of Sale only. Xicor, Inc. makes no warranty, express, statutory, implied, or by description regarding the information set forth herein or regarding the freedom of the described devices from patent infringement. Xicor, Inc. makes no warranty of merchantability or fitness for any purpose. Xicor, Inc. reserves the right to discontinue production and change specifications and prices at any time and without notice.
Xicor, Inc. assumes no responsibility for the use of any circuitry other than circuitry embodied in a Xicor, Inc. product. No other circuits, patents, licenses are implied.

## U.S. PATENTS

Xicor products are covered by one or more of the following U.S. Patents: 4,263,664; 4,274,012; 4,300,212; 4,314,265; 4,326,134; 4,393,481; 4,404,475; $4,450,402 ; 4,486,769 ; 4,488,060 ; 4,520,461 ; 4,533,846 ; 4,599,706 ; 4,617,652 ; 4,668,932 ; 4,752,912 ; 4,829,482 ; 4,874,967 ; 4,883$, 976 . Foreign patents and additional patents pending.

## LIFE RELATED POLICY

In situations where semiconductor component failure may endanger life, system designers using this product should design the system with appropriate error detection and correction, redundancy and back-up features to prevent such an occurence.
Xicor's products are not authorized for use in critical components in life support devices or systems.

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain
life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

[^0]:    Notes: (4)tpuR and tpuw are the delays required from the time $\mathrm{V}_{\mathrm{CC}}$ is stable until the specified operation can be initiated. These parameters are periodically sampled and not $100 \%$ tested.

